



Material Content Data Sheet



Sales Product Name		ESD102-U1-02ELS E6327		Issued		29. August 2013		
MA#		MA001059610						
Package		PG-TSSLP-2-3		Weight*		0.21 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.000	0.17		1670	
	noble metal	gold	7440-57-5	0.001	0.65		6469	
	inorganic material	silicon	7440-21-3	0.010	4.79	5.61	47945	56084
leadframe	non noble metal	nickel	7440-02-0	0.108	51.71	51.71	517148	517148
wire	non noble metal	copper	7440-50-8	0.001	0.68	0.68	6770	6770
encapsulation	organic material	carbon black	1333-86-4	0.000	0.19		1885	
	plastics	epoxy resin	-	0.011	5.46		54600	
	inorganic material	silicondioxide	60676-86-0	0.067	32.01	37.66	320071	376556
leadfinish	noble metal	gold	7440-57-5	0.004	1.76	1.76	17645	17645
plating	noble metal	palladium	7440-05-3	0.001	0.61		6119	
	noble metal	gold	7440-57-5	0.004	1.97	2.58	19678	25797
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com